

Localized crystallization of Germanium nanowires

- Travaux pratiques IVa, Applied Physics -
Master

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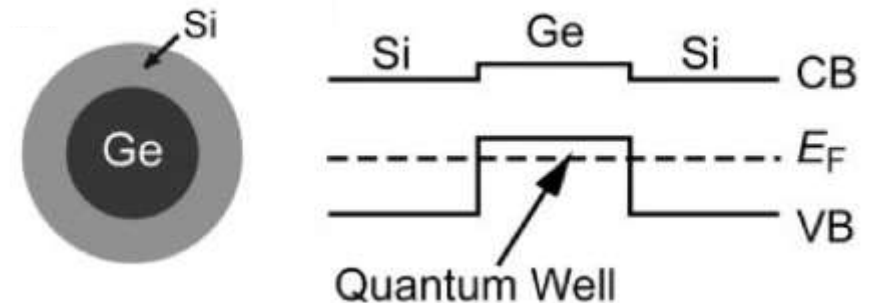
Motivations

Goal : Investigating which are the **best rapid thermal annealing (RTA) parameters** for **crystallizing** Germanium NWs

What we look for :

- Good **quality** and **defects free** crystal structure
- **Epitaxy** with the Silicon substrate
- Simple way to grow **nanowires networks**
- Possibility of **mass production**

What for : Ge-Si core-shell nanowires
quantum dots



Wei Lu et al. "One-dimensional hole gas in germaniumsilicon nanowire heterostructures". In: *Proceedings of The National Academy of Sciences - PNAS* (Jan. 2005)

NWs fabrication

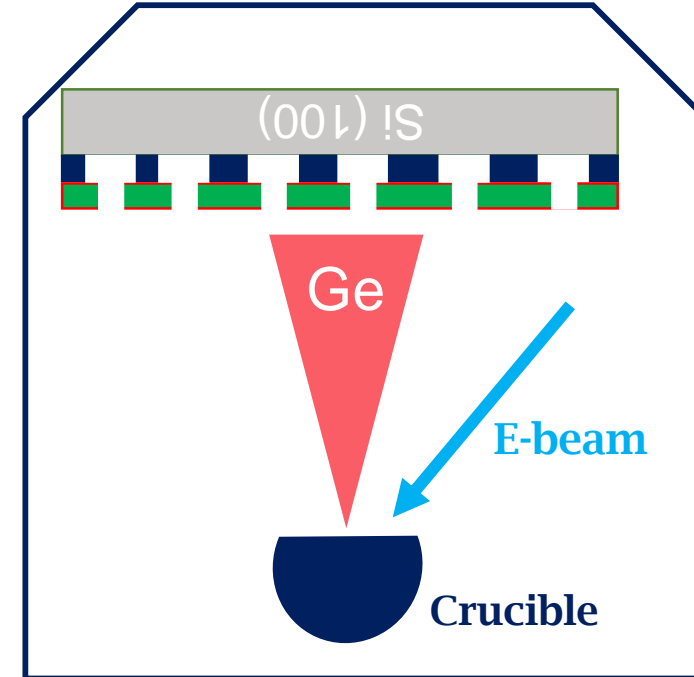
1) Spin coating
Ebeam resist



2) Ebeam exposure
and development



3) Ge deposition by evaporation



evaporator Leybold optics Lab 600H
(Ge 99,99%)

4) Development
(Lift-off)



5) Amorphous NWs

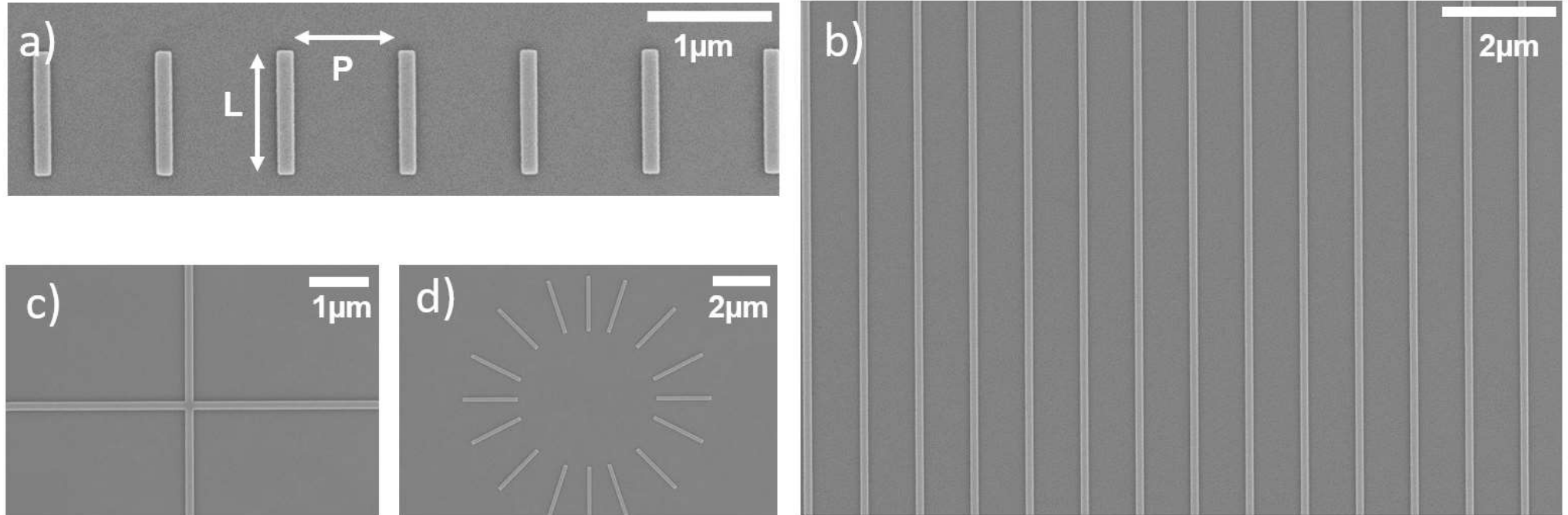


Evaporation and lift-off



- Simple way to grow **nanowires networks**
- Possibility of **mass production**

NWs fabrication



Pitch distance (P)

1 μm , 3 μm , 5 μm

Length of NWs (L)

1 μm , 5 μm , 10 μm , 25 μm , 50 μm

Width of NWs

45 nm, 65 nm, 95 nm, 135 nm

Height of NWs

20 nm

Orientation

100, 110, 010

Rapid Thermal Annealing
(RTA)

Solid Phase Epitaxy approach



JETFIRST 200

Performed series:

- 500°C for 10 sec
- 650°C for 10, 60, 120 sec
- 800°C for 10 sec

Analysis

Raman spectroscopy



- *Renishaw confocal Raman (PH dept.)*
- *Raman spectrometer (MX dept.)*

SEM and TEM (with EDX analysis)



Zeiss Merlin SEM



Talos F200S TEM

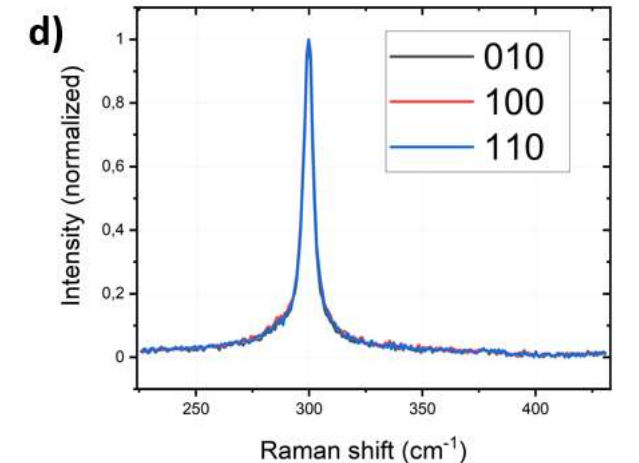
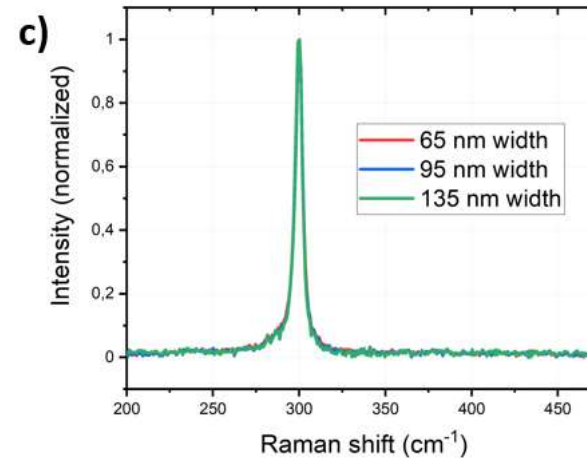
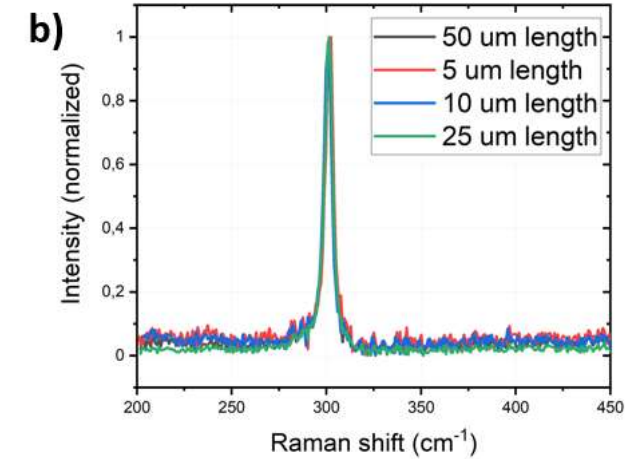
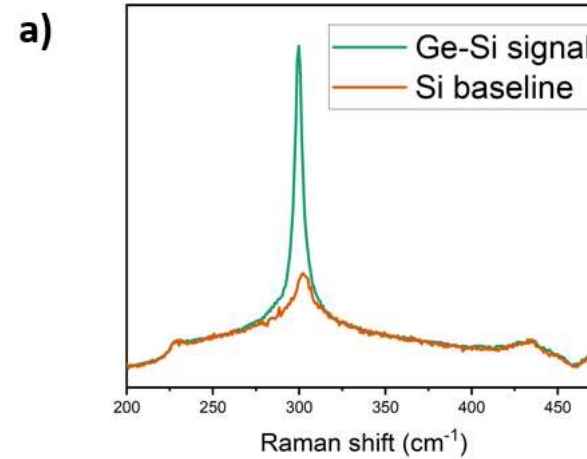
- [Talos™ F200S TEM for Materials Science \(thermofisher.com\)](https://www.thermofisher.com)
- [Metrology – Center of MicroNanotechnology CMi - EPFL](https://www.epfl.ch/research/centres-of-excellence/metrology/)
- [inVia™ confocal Raman microscope \(renishaw.com\)](https://www.renishaw.com)

Variations in crystal quality
as a function of NWs
morphology and
orientation

No significant differences



presence of an **oxide layer**

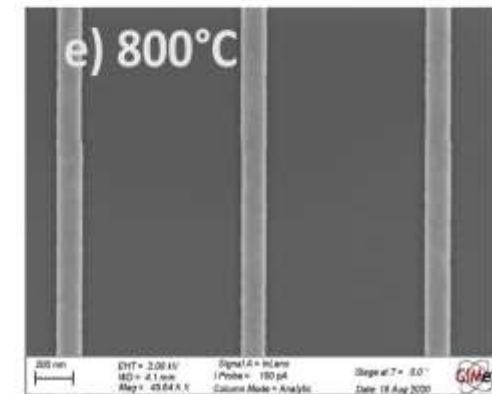
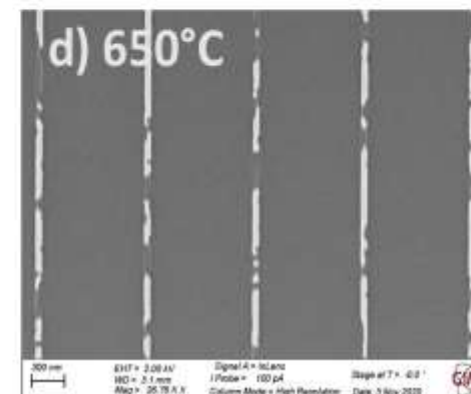
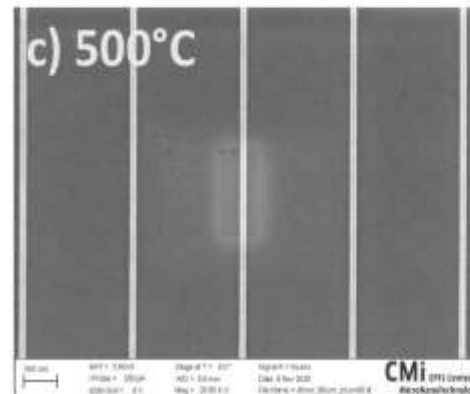
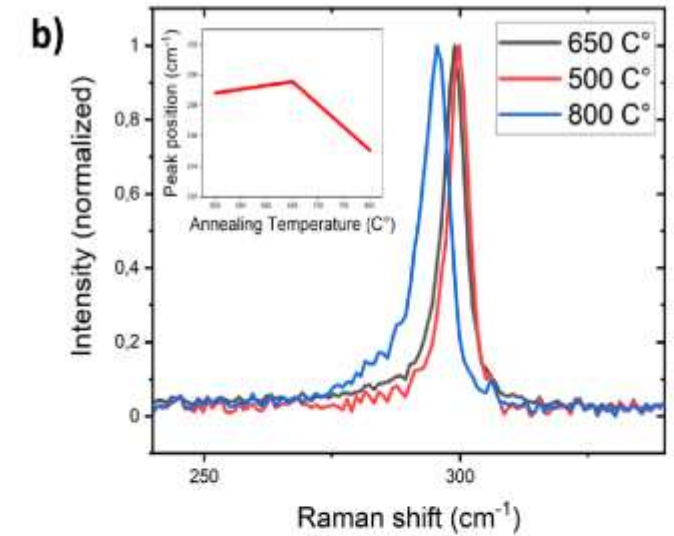
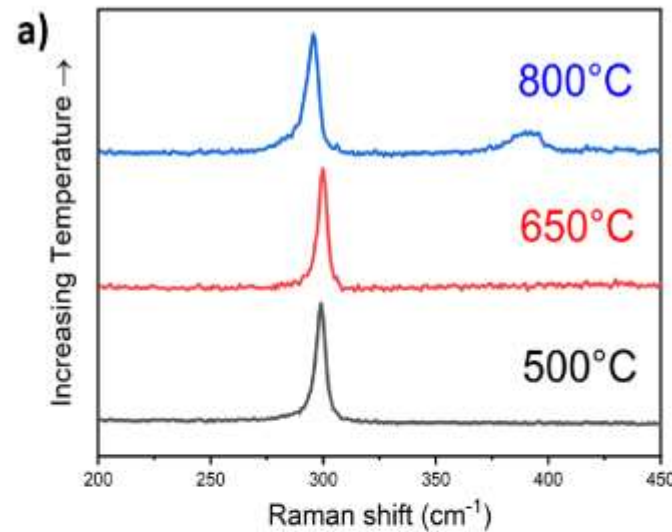


Results

Variation in crystal quality as a function of annealing temperature

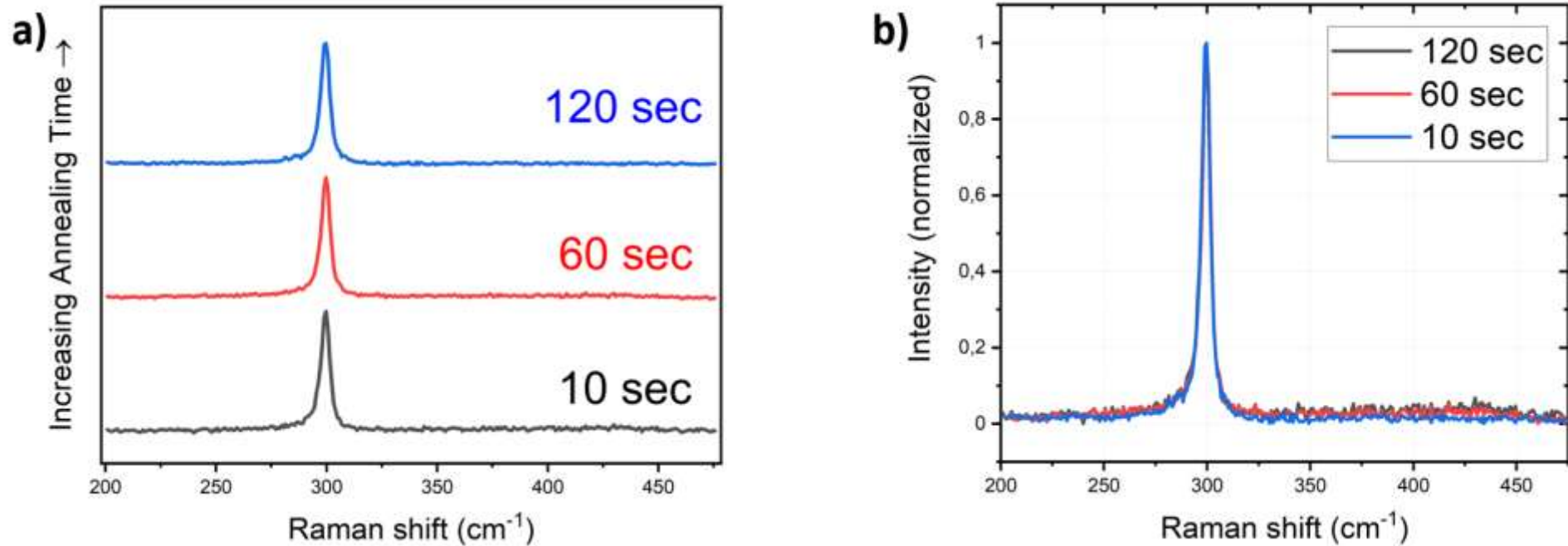
We observed:

- 650°C presented **cracks and holes**
- 800°C showed the presence of **intermixing**
- 800°C exhibited **peak shift and peak broadening**



Results

Variation in crystal quality as a function of annealing time
(Sample 650°C-120 sec)



No significant differences

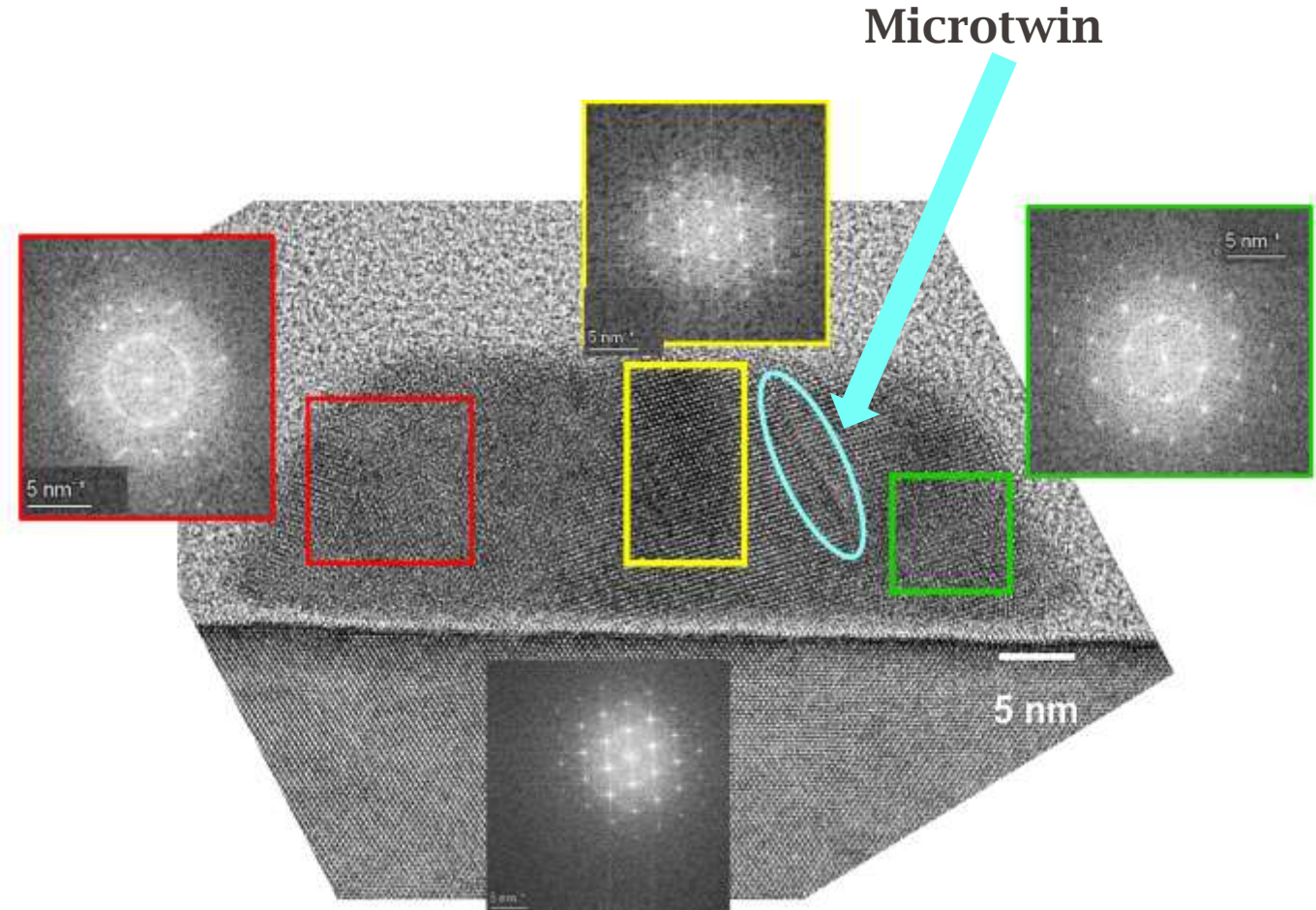
Results

TEM assessed:

- Polycrystallinity
- Presence of microtwins



oxide layer at the
interface

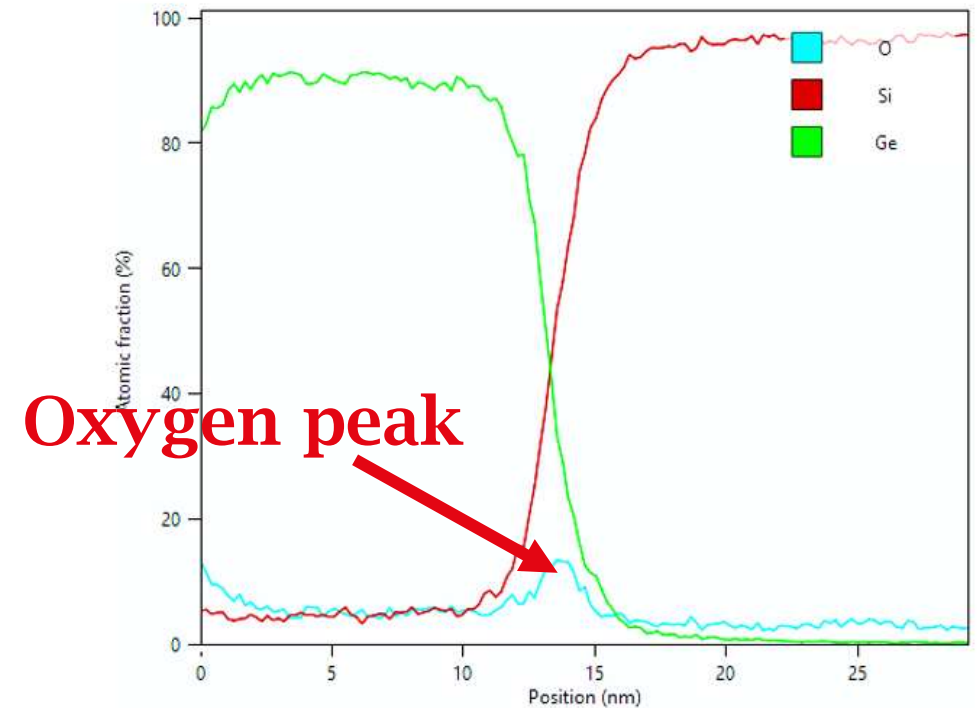
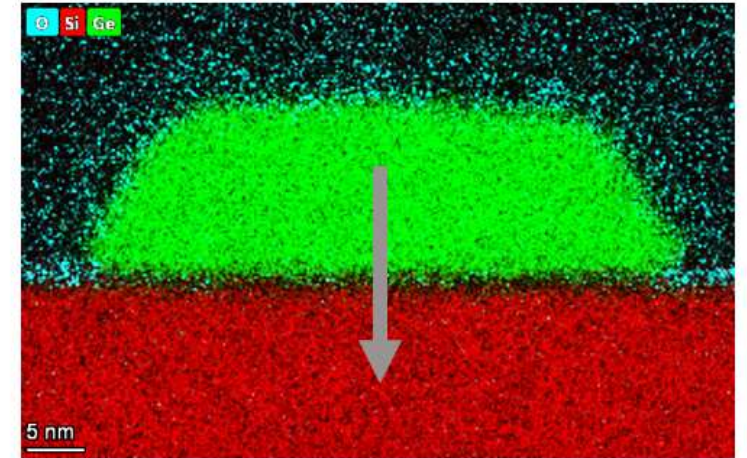


- Ichiro Mizushima et al. "Oxide-Mediated Solid Phase Epitaxy (OMSPE) of Silicon: A New Low-Temperature Epitaxy Technique Using Intentionally Grown Native Oxide". In: *Japanese Journal of Applied Physics* 39 (Apr. 2000)
- I. Mizushima et al. "Effect of interfacial oxide on solid-phase epitaxy of Si films deposited on Si substrates". In: *Journal of Applied Physics* 63, 1065 (1988)

Chemical characterization



presence of **Oxygen** at the interface



Conclusion

Best RTA parameters: 500°C - 10 seconds

Future goal: improving fabrication process:

- avoid the formation of an **oxyde layer**
- Achieve strain induced **mobility enhancement**
- Obtain **monocrystalline** and **defect free** crystal structures